

15 October 2002

09 1876,522

L Number	Hits	Search Text	DB	Time stamp
1	2661	205/125,170,181,183,184,187,205,210,220,221.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 13:51
2	563	205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 13:52
3	283	(205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 13:52
5	206	((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (circuitboard or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 15:30
6	149	((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (circuitboard or board)) and contact	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 15:31
7	135	(((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (circuitboard or board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 15:31
38	60	((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (printed adj wiring adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:41
40	42	((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (printed adj wiring adj board)) and contact	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:41
41	42	(((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (printed adj wiring adj board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:42
42	5	(((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (printed adj wiring adj board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)) and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 15:40
43	20	(((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (circuitboard or board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)) and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 15:40

44	20	((((((205/125,170,181,183,184,187,205,210,220,221.ccls. and (via or (through adj hole))) and electroless) and (printed adj wiring adj board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)) and barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:40
45	1219	438/597,667,674,678.ccls. and (via or (through adj hole))) and electroless) and (circuitboard or board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)) and barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:41
46	22	438/597,667,674,678.ccls. and (printed adj wiring adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:41
47	14	(438/597,667,674,678.ccls. and (printed adj wiring adj board)) and contact	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:42
48	8	((438/597,667,674,678.ccls. and (printed adj wiring adj board)) and contact) and (electroplate or electroplating or electrodeposit or electrodepositing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/15 17:42